Wi-Fi / System-on-Module Line Card

Laird Connectivity offers certified Wi-Fi modules that enable secure and reliable wireless connectivity, even in the harshest environments. Our modules are ideal for robust, business-critical connectivity in medical, industrial, and commercial settings where excellent RF performance, lower power consumption, simplified application development, and fast time to market are a must.

Laird CONNECTIVITY

Modules not actual size.	Sona™ IF573 (Coming Soon)	60 Series	Sterling-LWB5+	Sterling-LWB+	Sterling-EWB
Chipset	Infineon AIROC™ CYW55573	NXP 88W8997	Infineon CYW4373E	Infineon CYW43439	Infineon CYW4343W + STM32F412 Cortex M4 MCU
802.11 Standards	2x2 802.11a/b/g/n/ac/ax (Wi-Fi 6E)	802.11 a/b/g/n/ac (2.4 and 5 GHz)	802.11a/b/g/n/ac (2.4 and 5 GHz)	802.11a/b/g/n (2.4 GHz)	802.11 b/g/n
BT Standards	Bluetooth 5.2 - Dual Mode Classic (EDR) & BLE	Bluetooth 5.1 - Dual Mode Classic (EDR) & BLE	Bluetooth 5.2 - Dual Mode Classic (EDR) & BLE	Bluetooth 5.2 - Dual Mode Classic (EDR) & BLE	Bluetooth 5.1 - Dual Mode Classic (EDR) & BLE
Type	M.2 1318 SMT & M.2 2230 E-Key Module	SiP Package, M.2 2230-E Module with USB, SDIO, and PCIE variants	Surface Mount Module, M.2 2230 E-Key, USB-A Dongle	SiP Package, Surface Mount Module, M.2 2230 E-Key	SiP Package or Surface Mount Module
Size (mm)	13 x 18 x 0.43 (M.2 1318) 22 x 30 x 2.7 (M.2 2230 E-Key)	14 x 13 mm (SIP) 22 x 30 x 3.3 mm (M.2 E-Key)	12 x 17 x 2.2 mm (SMT PCB) 22 x 30 x 2.9 mm (M.2 E-Key) 17.5 x 47 x 11.7 mm (USB)	12 x 12 x 3 mm (SiP) 21 x 15 x 4 mm (PCB) 22 x 30 x 2.3 (M.2 PCB)	10 x 10 mm (SIP) 16 x 21 mm (PCB)
Tx Power (dBm)	Up to +18 dBm	Wi-Fi: 10 to 18 BT/BLE: 7 to 10	+ 18 dBm (maximum)	+ 18 dBm (maximum)	Wi-Fi: 12.5 to 17.5 BT/BLE: 4 to 8.5
Rx Sensitivity (dBm)	TBD	Wi-Fi: -55 to -95 BT/BLE: -88 to -95	Wi-Fi: -96 BT/BLE: -94	Wi-Fi: -89 to -94 BT/BLE: -83 to -91	Wi-Fi: -72 to -88 BT/BLE: -87 to -94
Temp. Range	-40°C to +85°C	-30°C to +85°C	-40°C to +85°C	-40°C to +85°C	-40° to +85° C
OS Support	Android, Linux	Android, Linux	Android, Linux, RTOS	Android, Linux, RTOS	On-board RTOS with WICED
Wi-Fi Security	WPA2-Personal, WPA2-Enterprise, WPA3-Personal, WPA3-Enterprise	WPA2-Personal, WPA2-Enterprise, WPA3-Personal, WPA3-Enterprise	WPA2-Personal, WPA2-Enterprise, WPA3-Personal, WPA3-Enterprise	WPA2-Personal, PA2-Enterprise, WPA3-Personal, WPA3-Enterprise	WPA2-Personal
Certifications	FCC, IC, CE, UKCA, MIC, RCM, Bluetooth SIG	FCC, IC, CE, UKCA, MIC, AU/NZ, KCC, RCM, Bluetooth SIG	FCC, IC, CE, UKCA, MIC, KCC, TW, AUS, BR, Bluetooth SIG	FCC, IC, CE, UKCA, MIC, KCC, RCM, BR, Bluetooth SIG	FCC, IC, CE, UKCA, MIC, RCM, Bluetooth SIG
Board Support Package	Kernel Backports, NetworkManager, Summit Supplicant — broad kernel, BSP, and MPU compatibility.	Kernel Backports, NetworkManager, Summit Supplicant and Yocto layer for Linux — broad kernel, BSP, and MPU compatibility.	Kernel Backports, NetworkManager, and Yocto layer for Linux ensures broad kernel, BSP, and MPU compatibility.	Kernel Backports, NetworkManager, and Yocto layer for Linux ensures broad kernel, BSP, and MPU compatibility.	WICED SDK and AT Command Set

- Designed for Mission Critical applications
- 'Always-On Connectivity' through advanced software
- Performance in harsh RF environments
- Multi-OS (Android/Linux)
- Enterprise Security
- Fast scanning & roaming
- Industry-leading Support & Extended Warranty
- Designed for **Fast Time-to-Market**
- Broad Certifications
- Innovative Development Tools & Resources
- Industry-leading Design Support

SUMMIT SUITE

To learn more, visit l**airdconnect.com/wi-fi** or contact us at **sales@lairdconnect.com**